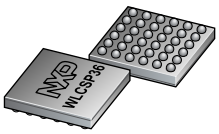


SOT2011-1

WLCSP36, wafer level chip scale package, 36 terminals, 0.3 mm pitch, 1.895 mm x 1.895 mm x 0.38 mm body (backside coating included)

15 February 2020 Package information

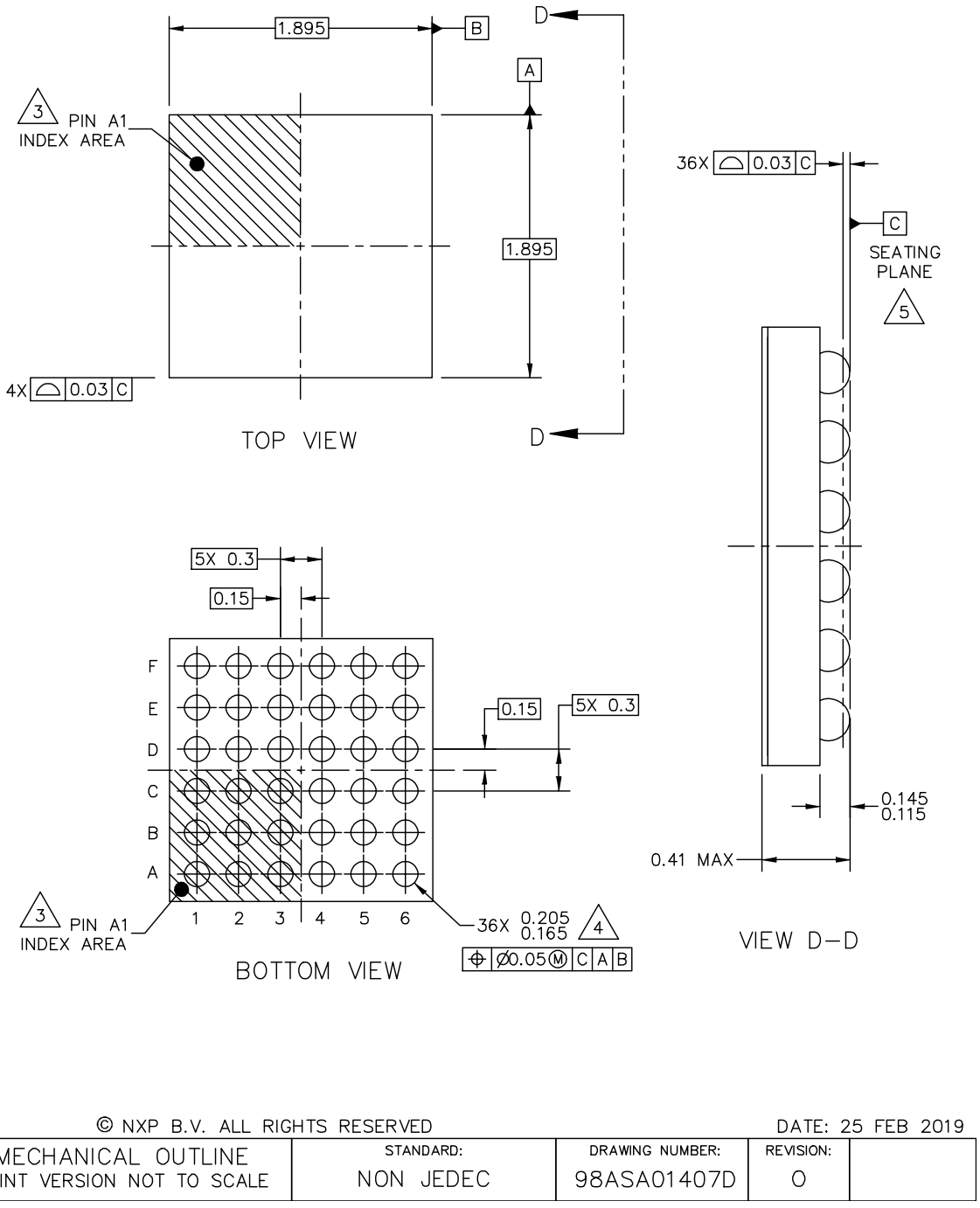
1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	25-02-2019
Manufacturer package code	98ASA01407D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.865	1.895	1.925	mm
package width	1.865	1.895	1.925	mm
package height	-	0.38	0.41	mm
nominal pitch	-	0.3	-	mm
actual quantity of termination	-	36	-	

2 Package outline



DATE: 25 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01407D	REVISION: O	

Figure 1. Package outline WLCSP36 (SOT2011-1))

WLCSP36, wafer level chip scale package, 36 terminals, 0.3 mm pitch, 1.895 mm x 1.895 mm x 0.38 mm body (backside coating included)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALL
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

DATE: 25 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01407D	REVISION: O	

Figure 2. Package outline note WLCSP36 (SOT2011-1))

3 Legal information

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SOT2011-1

WLCSP36, wafer level chip scale package, 36 terminals, 0.3 mm pitch, 1.895 mm x 1.895 mm x 0.38 mm body (backside coating included)

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For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 15 February 2020